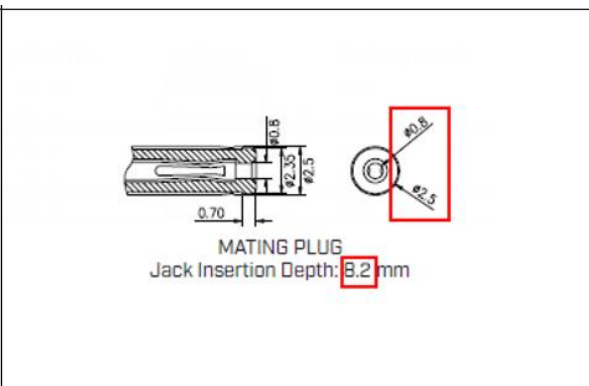
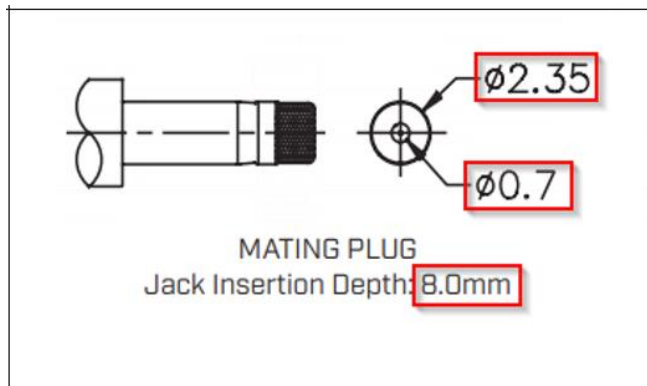




	MATERIAL	PLATING
center pin	brass	silver
terminal 1	brass	silver
terminal 2	copper alloy	silver
terminal 3	brass	silver
plastic	PA6T or equivalent	

DESCRIPTION	MATERIAL	PLATING/COLOR
center pin	copper alloy	silver
terminal 1	copper alloy t=0.30	silver
terminal 2	copper alloy t=0.25	silver
terminal 3	copper alloy t=0.25	silver
housing	PA10T (UL94V-0)	black



**SPECIFICATIONS**

parameter	conditions/description	min	typ	max	units
rated input voltage			24		Vdc
rated input current			2.5		A
contact resistance <sup>1</sup>	between terminal and mating plug		50		mΩ
insulation resistance	between terminal in a closed circuit		30		MΩ
insulation resistance	at 500 Vdc	100			MΩ
voltage withstand	for 1 minute		500		Vdc
insertion/withdrawal force		0.3		3	kg
operating temperature		-25		85	°C
life	at a rate of 24 cycles/minute		5,000		cycles
flammability rating	UL94V-0				
RoHS	yes				

**SPECIFICATIONS**

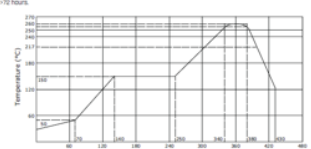
parameter	conditions/description	min	typ	max	units
rated input voltage			24		Vdc
rated input current			2.5		A
contact resistance	between terminal and mating plug		50		mΩ
insulation resistance	between terminal in a closed circuit		30		MΩ
insulation resistance	at 500 Vdc	100			MΩ
voltage withstand	for 1 minute		500		Vdc
insertion/withdrawal force		0.3		3	kg
operating temperature		-25		85	°C
life	at a rate of 24 cycles/minute		5,000		cycles
flammability rating	UL94V-0				
RoHS	yes				

**SOLDERABILITY**

parameter	conditions/description	min	typ	max	units
reflow storage	at relative humidity <math>\leq 80\%</math>		40		°C
reflow soldering <sup>2</sup>	see reflow profile	255	260	265	°C

drying conditions<sup>3</sup>  
parts in reel: bake at 40°C ±5°C for 72 hours  
parts removed from reel: bake at 40°C ±5°C for 10 hours

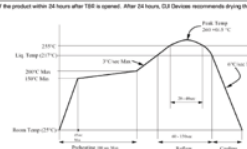
note:  
3. Must reflow solder within 72 hours from opening vacuum packaging at a temperature <math>< 30\text{°C}</math> @ relative humidity <math>\leq 80\%</math>.  
4. when exceeding floor life by <math>\geq 72</math> hours.

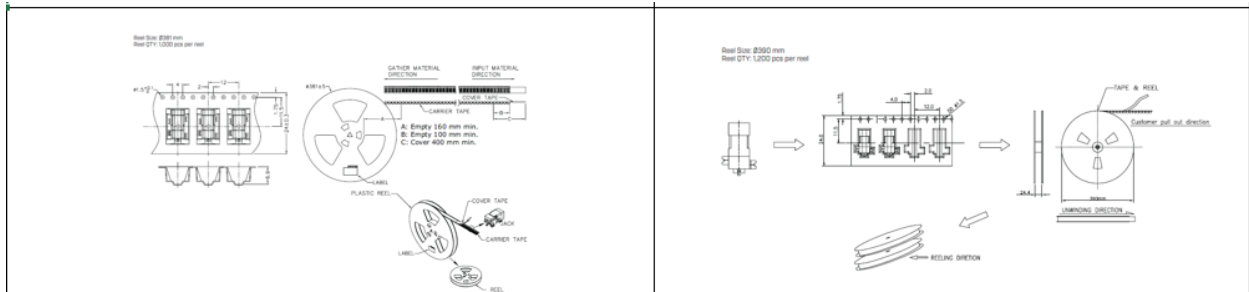


**SOLDERABILITY**

parameter	conditions/description	min	typ	max	units
reflow storage	540°C, <math>\leq 80\%</math> humidity		255	260	°C
reflow soldering	see reflow profile	255	260		°C

note:  
1. D32 Device recommends usage of the product within 24 hours after TSS is opened. After 24 hours, D32 Device recommends drying the parts prior to use.





Affected Date Code: *2/23/23*

Product Availability: *Channel Availability Q2*

Additional Information:

PCN Approval:

Operations/Quality



Product Management

